

Title (en)
Micromechanical element.

Title (de)
Mikromechanisches Element.

Title (fr)
Élément micromécanique.

Publication
EP 0478956 A2 19920408 (DE)

Application
EP 91114504 A 19910829

Priority
DE 4031248 A 19901004

Abstract (en)
The invention relates to a microchemical element, consisting of a substrate, a microstructure body, which is bonded to the substrate and can move partially with respect to it as a result of a temperature change and, for its part, is constructed from an electrically non-conductive and an electrically conductive material, at least a portion of the electrically conductive material forming a heating resistor. The object of the invention is to specify such an element of this type in which the movement of the microstructure body takes place parallel to the substrate. The object is achieved in that the heating resistor is arranged asymmetrically offset, seen in the vertical direction onto the substrate, in the moving part of the microstructure body, and is completely immersed in the microstructure body, its thickness in the specified direction corresponding to the thickness of the microstructure body.

Abstract (de)
Die Erfindung betrifft ein mikrochemisches Element, bestehend aus einem Substrat, einem am Substrat haftenden, gegenüber diesem durch Temperaturänderung teilweise beweglichen Mikrostrukturkörper, der seinerseits aus einem elektrisch nicht leitenden und aus einem elektrisch leitenden Material aufgebaut ist, wobei zumindest ein Teil des elektrisch leitenden Materials einen Heizwiderstand bildet. Aufgabe der Erfindung ist, ein solches Element dieser Art anzugeben, bei dem die Bewegung des Mikrostrukturkörpers parallel zum Substrat erfolgt. Die Aufgabe wird dadurch gelöst, daß der Heizwiderstand im beweglichen Teil des Mikrostrukturkörpers in senkrechter Richtung auf das Substrat gesehen asymmetrisch versetzt angeordnet und vollständig im Mikrostrukturkörper versenkt ist, wobei seine Dicke in der angegebenen Richtung der Dicke des Mikrostrukturkörpers entspricht. <IMAGE>

IPC 1-7
H01H 1/00; H01H 61/013

IPC 8 full level
H01H 1/00 (2006.01); **H01H 61/013** (2006.01)

CPC (source: EP)
H01H 1/0036 (2013.01); **H01H 61/013** (2013.01); **H01H 2061/006** (2013.01)

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Designated contracting state (EPC)
AT BE CH FR GB LI NL

DOCDB simple family (publication)
EP 0478956 A2 19920408; EP 0478956 A3 19921125; EP 0478956 B1 19950517; AT E122816 T1 19950615; DE 4031248 A1 19920409; DE 4031248 C2 19920723

DOCDB simple family (application)

